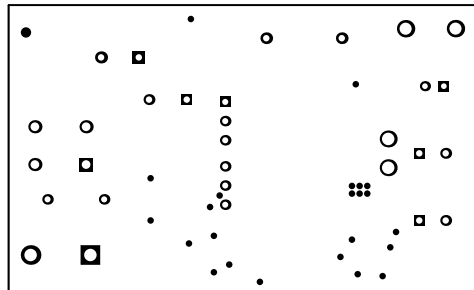
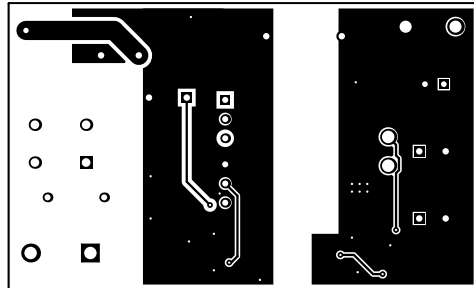


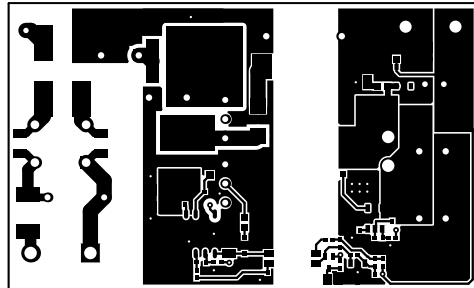
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 5/31/2017	5:55:39 PM	TEXAS INSTRUMENTS



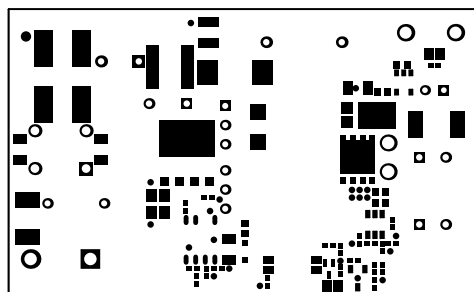
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 5/31/2017 5:55:42 PM	TEXAS INSTRUMENTS	



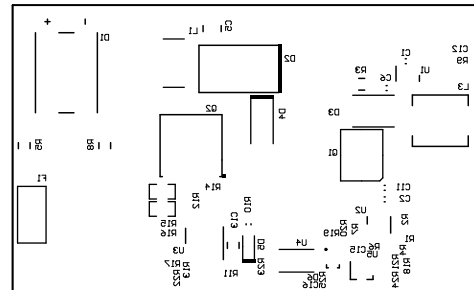
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 5/31/2017 5:55:45 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 5/31/2017 5:55:48 PM	TEXAS INSTRUMENTS	

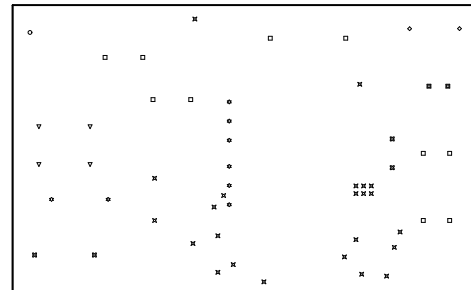


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/31/2017 5:55:51 PM	TEXAS INSTRUMENTS	

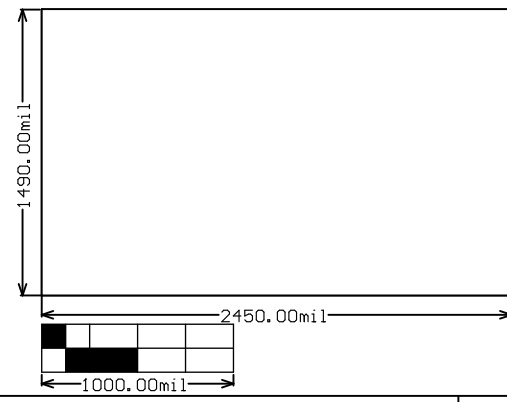


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 5/31/2017 5:55:54 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⊠	23	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
○	1	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
■	2	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
☆	8	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
□	10	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
◇	2	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	4	64.96mil (1.650mm)	PTH	Round	Top Layer - Bottom Layer	
	54 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 5/31/2017	5:55:57 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11500	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 5/31/2017 5:56:01 PM	TEXAS INSTRUMENTS	

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